

NOT RECOMMENDED FOR NEW DESIGN USE DMP3007LK3



DMP3010LK3

P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on) max}	I _D T _A = +25°C	
201/	8mΩ @ Vgs = -10V	-17A	
-30V	$10.2 \text{m}\Omega$ @ $V_{GS} = -4.5 \text{V}$	-14.5A	

Description

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- DC-DC Converters
- Power Management Functions
- Backlighting

Features and Benefits

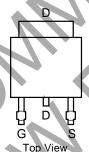
- Low Input Capacitance
- Low On-Resistance
- Fast Switching Speed
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

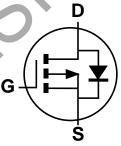
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish—Tin Finish annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208e3
- Weight: 0.33 grams (approximate)



Top View



Top View Pin-Out



Equivalent Circuit

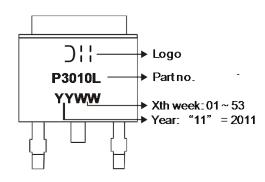
Ordering Information (Note 4 & 5)

Part Number	Compliance	Case	Packaging
DMP3010LK3-13	Standard	TO252	2500/Tape & Reel
DMP3010LK3Q-13	Automotive	TO252	2500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q10x qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html

Marking Information





Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V_{DSS}	-30	V		
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Proje Current (Note 7) \/ 40\/	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	-17.0 -13.0	Α
Continuous Drain Current (Note 7) V _{GS} = -10V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	-27.0 -21.0	Α
Continuous Drain Current (Note 7) V _{GS} = -4.5V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	-14.5 -11.5	Α
Continuous Drain Current (Note 7) VGS = -4.5V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	-23.0 -18.0	Α
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I _{DM}	-100	Α		
Maximum Body Diode Forward Current (Note 7)	Is	5.5	Α		
Avalanche Current (Note 8)	IAS	47	Α		
Avalanche Energy (Note 8)	Eas	113	mJ		

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Total Power Dissipation (Note 6)			P _D	1.7	W
Thermal Resistance, Junction to Ambient (Note 6)		Steady state	5	72	°C/W
mermai Resistance, Junction to Ambient (Note 6)		t<10s	$R_{\theta JA}$	29	°C/W
Total Power Dissipation (Note 7)			P_{D}	3.4	W
Thermal Resistance, Junction to Ambient (Note 7)	1	Steady state	Р	37	°C/W
Thermal Resistance, Junction to Ambient (Note 1)		t<10s	$R_{\theta}JA$	15	°C/W
Operating and Storage Temperature Range			$T_{J_i}T_{STG}$	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

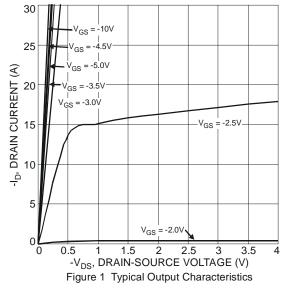
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV _{DSS}	-30		1	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	IDSS	-	1	-1	μΑ	$V_{DS} = -30V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}		_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V _{GS(th)}	-1.1	-1.6	-2.1	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$	
Static Drain-Source On-Resistance		l	6.5	8	mΩ	$V_{GS} = -10V, I_D = -10A$	
Static Dialif-Source Off-Resistance	R _{DS} (ON)	_	7.2	10.2		$V_{GS} = -4.5V, I_D = -10A$	
Forward Transfer Admittance	Y _{fs}	_	30	_	S	$V_{DS} = -15V, I_{D} = -10A$	
Diode Forward Voltage	V _{SD}	_	-0.65	-1.0	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	Ciss	l	6234	1		V _{DS} = 15V, V _{GS} = 0V f = 1.0MHz	
Output Capacitance	Coss	_	1500		pF		
Reverse Transfer Capacitance	C _{rss}	_	774	_			
Gate Resistance	R _G	_	1.28	_	μ	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge	Qg		59.2	_			
Gate-Source Charge	Qgs	_	16.1	_	nC	$V_{DS} = -15V, V_{GS} = -4.5V,$ $I_{D} = -10A$	
Gate-Drain Charge	Q_{qd}	_	15.7	_		ID = -10A	
Turn-On Delay Time	t _{D(on)}	_	11.4	_			
Turn-On Rise Time	t _r	_	9.4	_		$V_{DS} = -15V, V_{GEN} = -10V,$	
Turn-Off Delay Time	t _{D(off)}	_	260.7	_	ns	$R_G = 6\Omega$, $I_D = -1A$	
Turn-Off Fall Time	t _f	_	99.3	_			

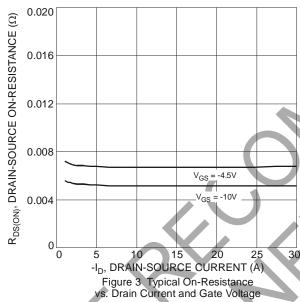
Notes:

- 6. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 7. Device mounted on FR-4 substrate PCB, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 8. UIS in production with L = 0.1mH, T_J = +25°C.
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to production testing.









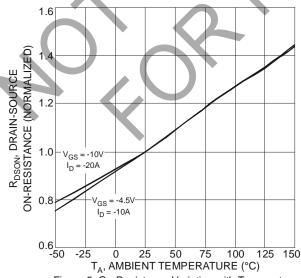
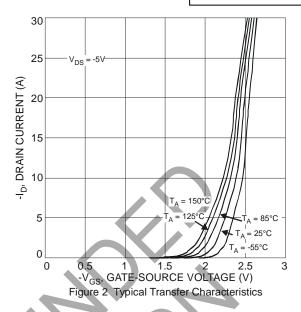
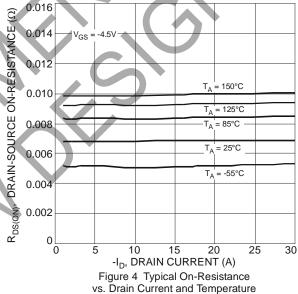


Figure 5 On-Resistance Variation with Temperature





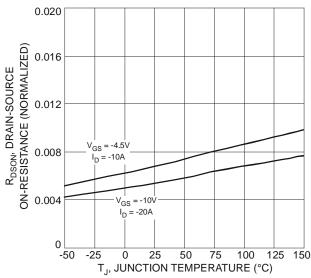


Figure 6 On-Resistance Variation with Temperature



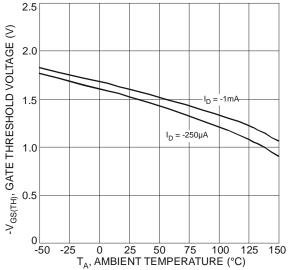
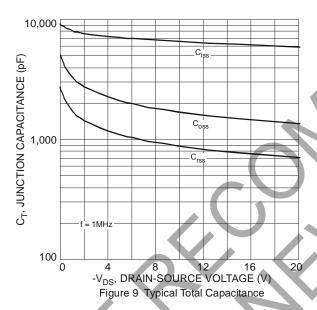


Figure 7 Gate Threshold Variation vs. Ambient Temperature



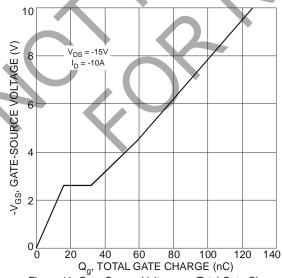
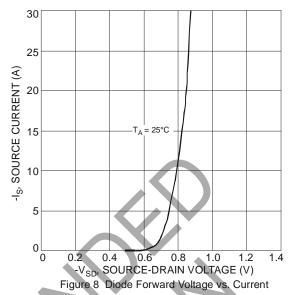


Figure 11 Gate-Source Voltage vs. Total Gate Charge



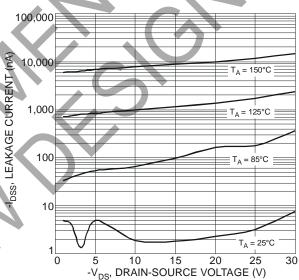
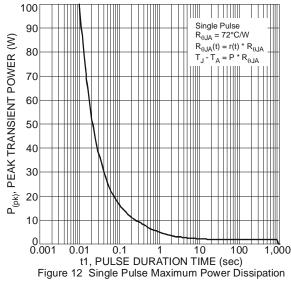
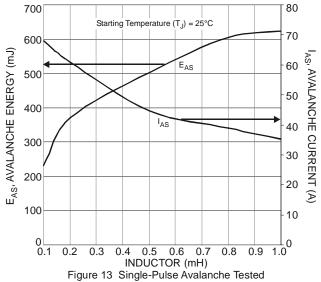
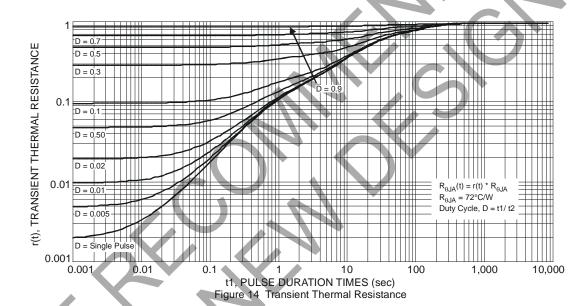


Figure 10 Typical Leakage Current vs. Drain-Source Voltage





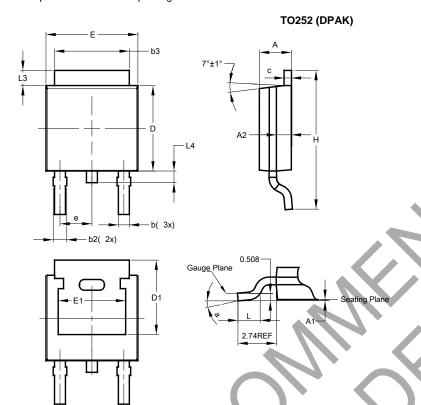






Package Outline Dimensions

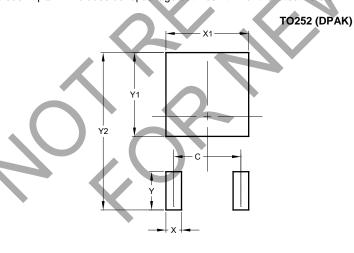
Please see http://www.diodes.com/package-outlines.html for the latest version.



TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
A1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b 3	5.21	5.46	5.33		
O	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21		I		
е		ļ	2.286		
Е	6.45	6.70	6.58		
E1	4.32		—		
Ŧ	9.40	10.41	9.91		
ŕ	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
7	0.64	1.02	0.83		
a	0°	10°	_		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)			
С	4.572			
Х	1.060			
X1	5.632			
Υ	2.600			
Y1	5.700			
Y2	10.700			



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